

BSP372NH6327-VB Datasheet N-Channel 100-V (D-S) MOSFET

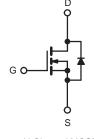
PRODU	CT SUMMARY	
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)
100	0.100 at V _{GS} = 10 V	5.0
100	0.120 at V _{GS} = 4.5 V	4.5

FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- TrenchFET[®] Power MOSFETs
- 175 °C Maximum Junction Temperature
- Compliant to RoHS Directive 2002/95/EC







N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	T _A = 25 °C, unle	ss otherwise r	noted		
Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		V _{DS}	100		V
Gate-Source Voltage		V _{GS}	± 20		v
Continuous Drain Current (T _{.1} = 175 °C) ^a	T _A = 25 °C	I _D	5.0	4.5	
Continuous Drain Current $(T_j = T/5 C)$	T _A = 70 °C		3.5	3.0	А
Pulsed Drain Current		I _{DM}	25		A
Avalanche Current		I _{AS}	15		
Single Pulse Avalanche Energy		E _{AS}	11		mJ
Maximum Dawar Dissinctional	T _A = 25 °C	P _D	3.3	1.7	W
Maximum Power Dissipation ^a	T _A = 70 °C	۰D	2.3	1.2	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55	to 175	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum hursting to Archiest a	t ≤ 10 s	R _{thJA}	36	45	
Maximum Junction-to-Ambient ^a	Steady State	i thJA	75	90	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	17	20	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	Symbol		IVIII.	тур.	IVIAX.	Unit
	V	$V_{GS} = 0 V, I_D = 250 \mu A$	400			
Drain-Source Breakdown Voltage	V _{DS}	66 5 1	100			V
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	1.5		3	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V$, $V_{GS} = \pm 20 V$			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA
Zero Gale voltage Drain Guirent	·D22	V_{DS} = 100 V, V_{GS} = 0 V, T_{J} = 55 °C			20	μΛ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	40			А
		V _{GS} = 10 V, I _D = 6.0 A		0.110		
	Р	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 4.0 \text{ A}, \text{ T}_{J} = 125 \text{ °C}$		0.122		0
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 4.0 A, T _J = 175 °C		0.140		Ω
		V _{GS} = 4.5 V, I _D = 3.1 A		0.120		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 4.0 A		25		S
Diode Forward Voltage ^a	V _{SD}	I _S = 1.7 A, V _{GS} = 0 V		0.8	1.2	V
Dynamic ^b				•		
Total Gate Charge	Qg			18	27	
Gate-Source Charge	Q _{gs}	$V_{DS} = 50$ V, $V_{GS} = 10$ V, $I_{D} = 4.0$ A		3.4		nC
Gate-Drain Charge	Q _{gd}			5.3		
Gate Resistance	Rg	V _{GS} = 0.1 V, f = 5 MHz	0.5	1.4	2.4	Ω
Turn-On Delay Time	t _{d(on)}			10	20	
Rise Time	t _r	V_{DD} = 50 V, R_L = 30 Ω		10	20	
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong \text{1}$ A, V_GEN = 10 V, R_g = 6 Ω		25	50	ns
Fall Time	t _f			12	24	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 1.7 A, dl/dt = 100 A/μs		50	80	

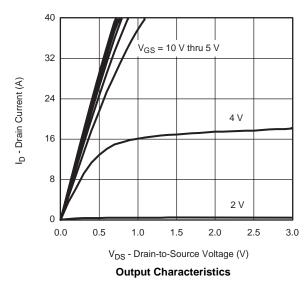
Notes:

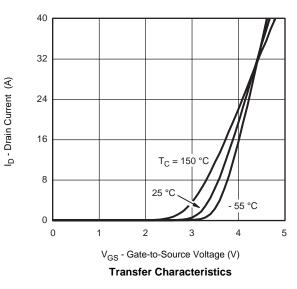
a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

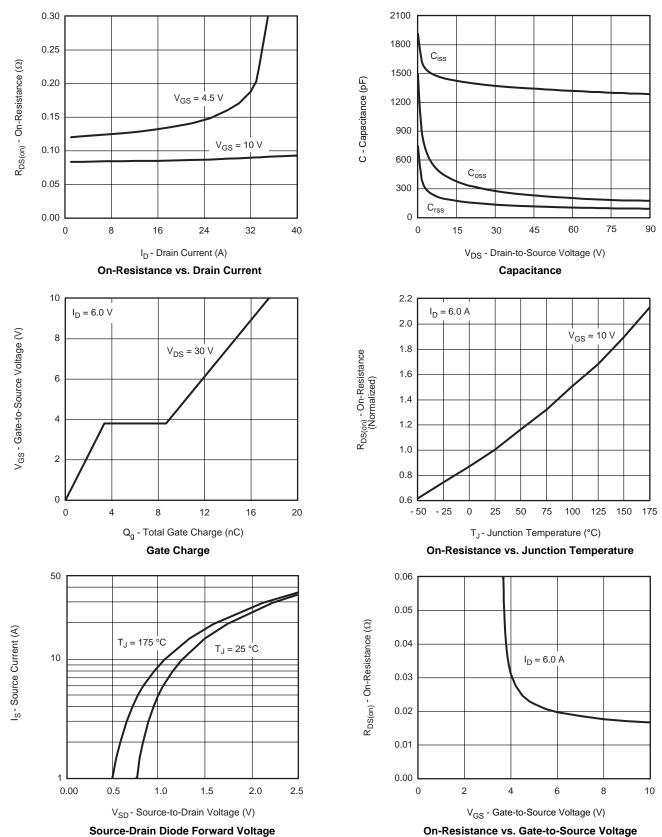




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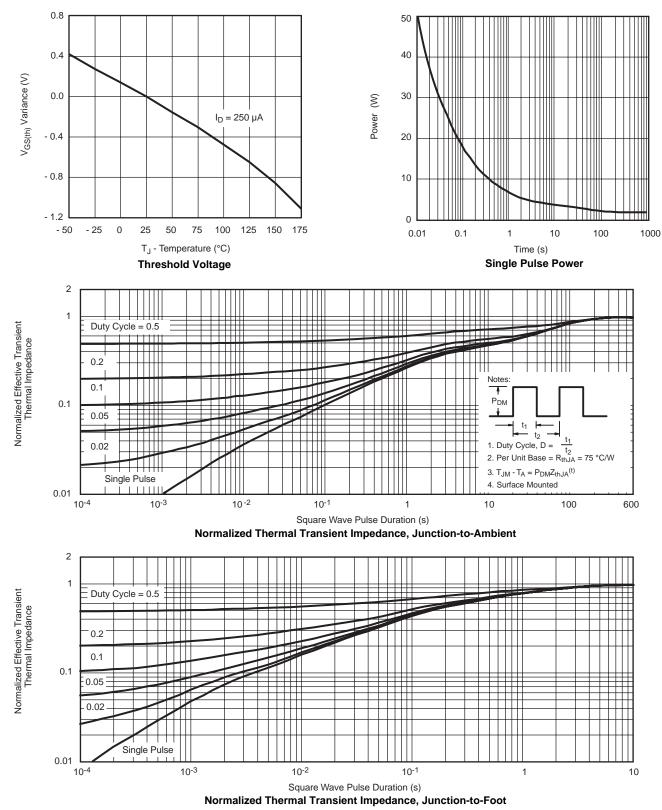


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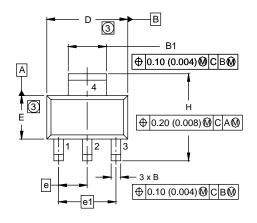


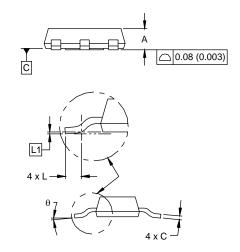
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SOT-223 (HIGH VOLTAGE)





DIM.	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
А	1.55	1.80	0.061	0.071	
В	0.65	0.85	0.026	0.033	
B1	2.95	3.15	0.116	0.124	
С	0.25	0.35	0.010	0.014	
D	6.30	6.70	0.248	0.264	
E	3.30	3.70	0.130	0.146	
е	2.30 BSC		0.0905 BSC		
e1	4.60 BSC		0.181 BSC		
Н	6.71	7.29	0.264	0.287	
L	0.91	-	0.036	-	
L1	0.061 BSC		0.002	4 BSC	
θ	-	10'	-	10'	

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.

2. Dimensions are shown in millimeters (inches).

3. Dimension do not include mold flash.

4. Outline conforms to JEDEC outline TO-261AA.



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